## **MA27D27**

### Silicon epitaxial planar type

#### For super high speed switching

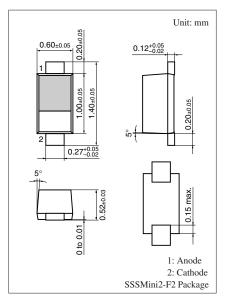
#### ■ Features

- Small reverse current I<sub>R</sub>
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>
- SSS-Mini type 2-pin package

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	20	V
Repetitive peak reverse voltage	$V_{RRM}$	20	V
Forward current (Average)	I <sub>F(AV)</sub>	100	mA
Peak forward current	$I_{FM}$	200	mA
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

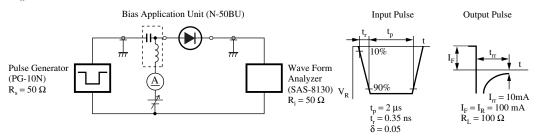


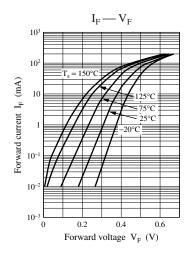
Marking Symbol: 8L

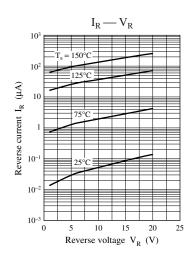
## ■ Electrical Characteristics $T_a = 25$ °C ± 3°C

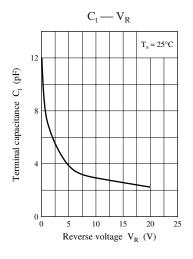
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 10 \text{ mA}$		0.38	0.44	V
	V <sub>F2</sub>	$I_F = 100 \text{ mA}$		0.54	0.58	
Reverse current	$I_R$	$V_R = 10 \text{ V}$			0.3	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		11		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Rated input/output frequency: 250 MHz
  - 4. \* : t<sub>rr</sub> measurement circuit









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